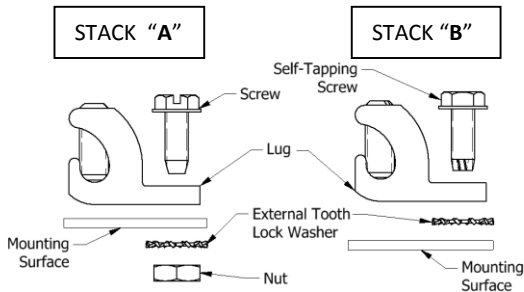


UL Listed and CSA Certified Grounding and Bonding Equipment* investigated in accordance to standard ANSI/UL 467, CSA C22.2 No. 41, NMX-J-590-ANCE.

UL Listed Ground Lugs and Devices for use with Photovoltaic Modules and Panels investigated in accordance to standard ANSI/UL 2703.



Mounting Requirements



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Figure 1: Minimum Hardware Required

CL501TNMHWSG1 and CL501DBKIT1 are packaged with required hardware as shown in stack "A"
 CL501TNMHWSST and CL501DBKIT2 are packaged with required hardware as shown in stack "B"
 CL501TN(BULK) and CL501TNMHWSS are approved with hardware stack "A" or "B" as shown above.

** For Grounding and Bonding applications per UL467/CSA 22.2 No. 41 use hardware stack "A".*

Cat No.	Max OCPD (A)	Mounting Surface					Mounting Screw		Mounting-Hole Size	Field Wiring		
		Stack Type	Min Thk (in)	Max Thk (in)	Mtl	Surface Prep	Size	Tightening Torque (in-lbs)		Wire Type	Wire Size (AWG)	Tightening Torque (in-lbs)
CL501TN CL501DBKIT2	150	B	.06"	.13"	AL	Anodized	10-32	25	#21 drill (.159")	Copper SOL. or STR.	14-10	20
	200		.13"	.13"	AL	Anodized						
CL501TN CL501DBKIT1	25	A	.06"	.25"	AL	Anodized	10-32	50	.200"±.010		8	25
CL501TN CL501DBKIT1	200	A	.06"	.25"	Steel	Galvanized	10-32	50			6-4	35

*Items may or may not include "W" suffix

Table 1: Mounting Surface Requirements

Important notes:

1. The NEC section 690.43 states, "Exposed non-current carrying metal parts of module frames, equipment, and conductor enclosures shall be grounded in accordance with 250.134 or 250.136 (A) regardless of voltage."
2. For Proper Equipment Grounding Conductor (EGC) and Overcurrent Protection Device (OCPD) sizing, refer to NEC sections 250.66, 250.122 and 250.166.